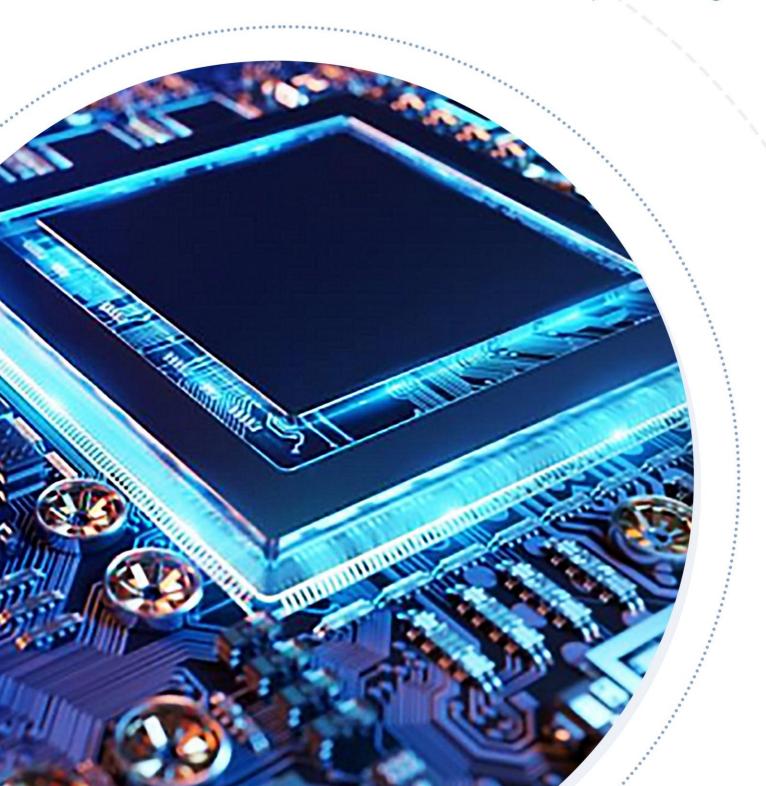
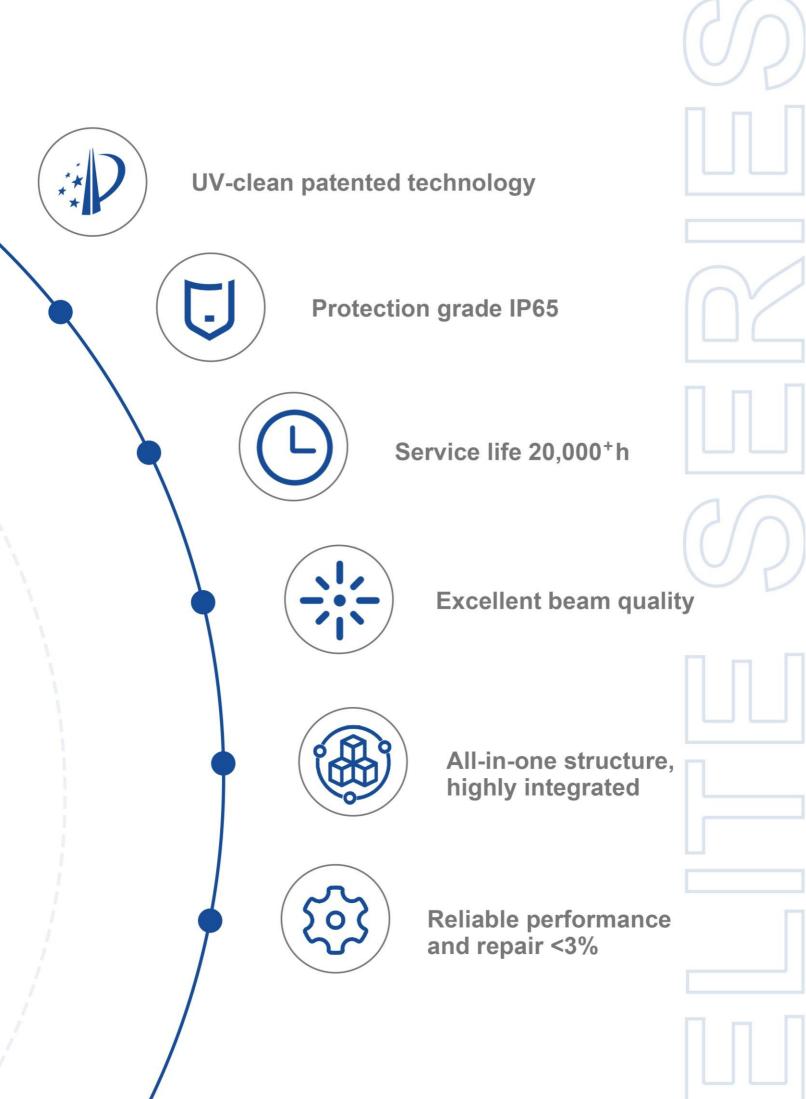


Elite series

Semiconductor processing





Elite series high energy UV laser



15W

The laser power

UV-clean

Patented technology

20000⁺h

The service life

Introduction

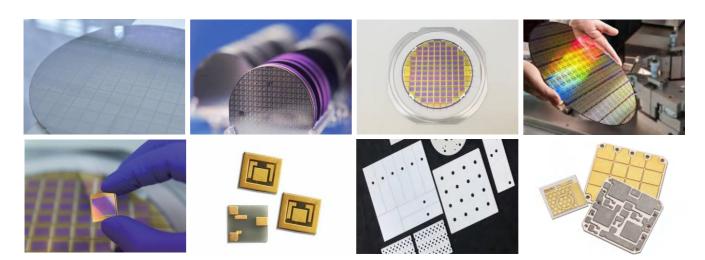
The high-energy ultraviolet laser, characterized by a wavelength of 355nm, features a single-pulse energy of 1.5mJ and a high peak power. It efficiently cuts SiC and diamond wafers, directly severing the wafers and metal layers with high efficiency and a minimal edge breakage (<2um).

Features

- The laser power is 15W;
- Adopt UV-clean patented technology to solve power attenuation worry free used;
- The service life exceeds 20000 hours, maintenance is free, and no need for regular commissioning or calibration;
- Excellent beam quality M² < 1.3, simple process, and higher efficiency;
- 3-layer protection, protection grade IP65, more suitable for harsh working environment;
- Rugged, easy to install, and easy to integrate.

Application

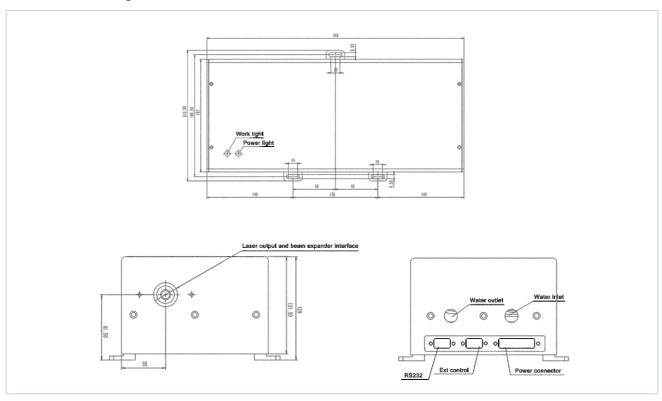
- Sic, diamond wafer scribing and drilling
- Ceramic scribing and drilling



Specifications

Model No.	MMEPU-355-15-HE			
Optical Characteristics				
Wavelength (nm)	355nm			
Average Power (W)	>15W@10kHz			
Single Pulse Energy (uJ)	~1500uJ@10kHz			
Pulse Width (ns)	30ns@10kHz			
Repitition Rate	10-20kHz			
Pulse Stability	<3% rms			
Long Term Stability	<±3%			
Beam Characteristics				
Polarization Ratio	Horizontal;>100:1			
Beam Diameter	~1mm(at exit)			
Beam Circularity	>90%			
Spatial Mode	TEM ₀₀ ,M ² <1.3			
Operating Specifications				
Warm-up Time	<15minutes from cold start			
Electrical Requirement	DC17.5V, 350W			
Ambient Temperature	10-35°C, RH<80%			
Storage Conditions	-10-40°C, RH<90%			
Physical Characteristics				
Cooling System	Water-Cooled			
Water Temperature (laser inlet)	25°C			

Dimensional Drawings



Elite series high power UV lasers



18-30W

The laser power

UV-clean

Patented technology

20000⁺h

The service life

Introduction

It has excellent power stability, ensuring long-term operation, and at the same time, has high single pulse energy, which can produce higher energy density quickly, thereby better handling materials with higher hardness, such as silicon carbide.

Features

- The laser power is 18-30W;
- Adopt UV-clean patented technology to solve power attenuation worry free used;
- The service life exceeds 20000 hours, maintenance is free, and no need for regular commissioning or calibration;
- Excellent beam quality M² < 1.3, simple process, and higher efficiency;
- 3-layer protection, protection grade IP65, more suitable for harsh working environment;
- Rugged, easy to install, and easy to integrate.

Application

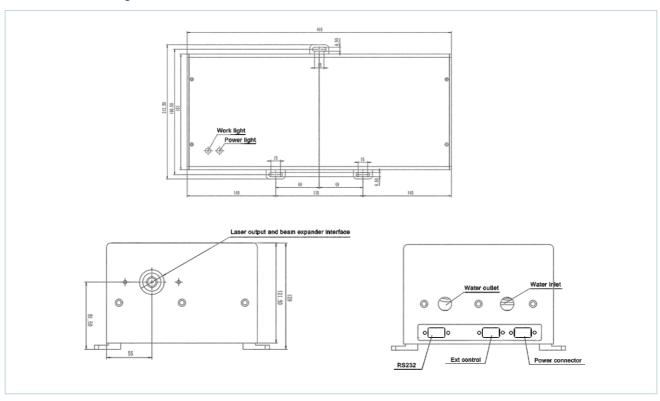
- Solar cell scribing
- PCB & FPC splitting and cutting
- Sic wafer scribing
- Film cutting



Specifications

Model No.	MMEPU-355-18	MMEPU-355-20	MMEPU-355-25	MMEPU-355-30	
Optical Characteristics					
Wavelength (nm)	355nm±1nm				
Average Power (W)	>18W@50kHz	>20W@50kHz	>25W@50kHz	>30W@50kHz	
Single Pulse Energy (uJ)	~350uJ@50kHz	~400uJ@50kHz	~500uJ@50kHz	~600uJ@50kHz	
Pulse Width (ns)	12ns@50kHz				
Repitition Rate	50-500kHz				
Pulse Stability	<3% rms				
Long Term Stability	<±3%				
Beam Characteristics					
Polarization Ratio	Horizontal;>100:1				
Beam Diameter	~1mm(at exit)/~6mm(6X beam expander)				
Beam Circularity	>90%				
Spatial Mode	TEM ₀₀ ,M ² <1.3				
Operating Specifications					
Warm-up Time	<15 minutes from cold start				
Electrical Requirement	DC24V, 600W				
Ambient Temperature	10-35℃, RH<80%				
Storage Conditions	-10-40°C, RH<90%				
Physical Characteristics					
Cooling System	Water-Cooled				
Water Temperature (laser inlet)	25℃				

Dimensional Drawings



Elite series high power green laser



30W

The laser power

UV-clean

Patented technology

20000⁺h

The service life

Introduction

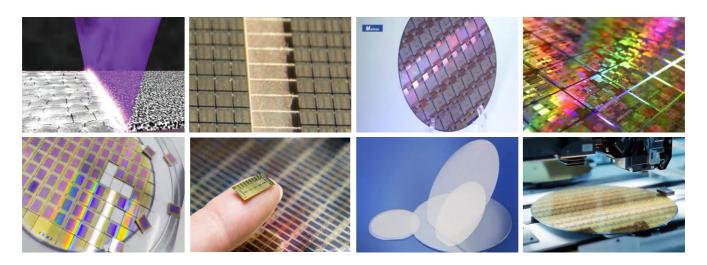
Its extremely high power stability guarantees long-term operation. At the same time, it has high single pulse energy, which can produce higher energy density in a short time, thus better dealing with materials with higher hardness such as SiC.

Features

- Adopt UV-clean patented technology to solve power attenuation worry free used;
- The service life exceeds 20000 hours, maintenance is free, and no need for regular commissioning or calibration;
- Excellent beam quality M² < 1.3, simple process, and higher efficiency;
- 3-layer protection, protection grade IP65, more suitable for harsh working environment;
- Rugged, easy to install, and easy to integrate.

Application

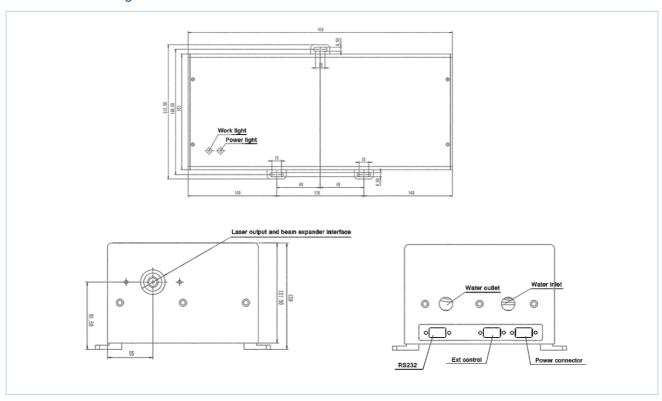
- Wafer annealing
- Wafer drilling and scribing



Specifications

M. LIN	MATERIA FOR 20			
Model No.	MMEPG-532-30			
Optical Characteristics				
Wavelength (nm)	532nm			
Average Power (W)	>30W@60kHz			
Single Pulse Energy (uJ)	~500uJ@60kHz			
Pulse Width (ns)	20ns@60kHz			
Repitition Rate	50-500kHz			
Pulse Stability	<3% rms			
Long Term Stability	<±3%			
Beam Characteristics				
Polarization Ratio	Vertical;>100:1			
Beam Diameter	6mm(Built in beam expander)			
Beam Circularity	>90%			
Spatial Mode	TEM ₀₀ ,M ² <1.3			
Operating Specifications				
Warm-up Time	<15minutes from cold start			
Electrical Requirement	DC24V,600W			
Ambient Temperature	10-35°C, RH<80%			
Storage Conditions	-10-40°C, RH<90%			
Physical Characteristics				
Cooling System	Water-Cooled			
Water Temperature (laser inlet)	25°C			

Dimensional Drawings



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